

/ Descriptions

TO-220

PNP

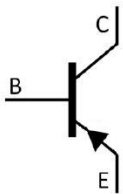
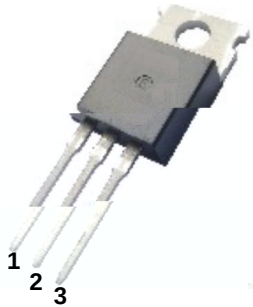
Silicon PNP transistor in a TO-220 Plastic Package.

/ Features

- MJE15034

High DC current gain, High V_{CEO} , High f_T , Complementary pair with MJE15034.**/ Applications**

Designed for us as high-frequency drivers in audio amplifiers.

/ Equivalent Circuit**/ Pinning**

PIN1 Base

PIN 2 Collector

PIN 3 Emitter

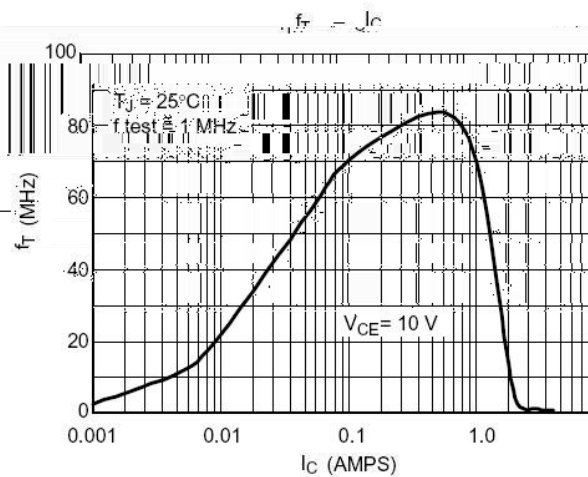
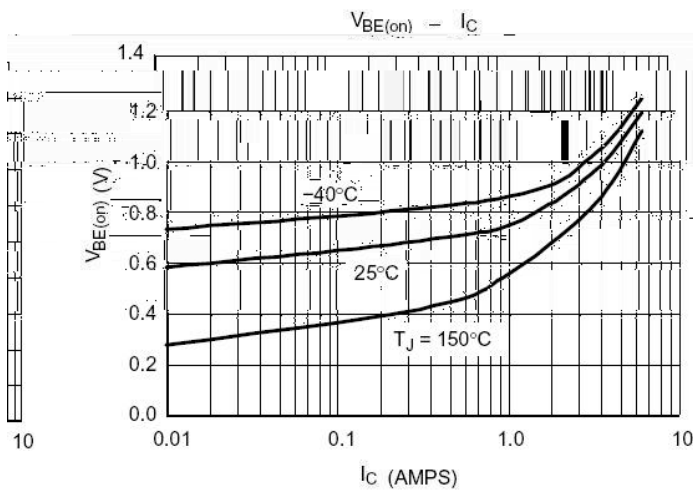
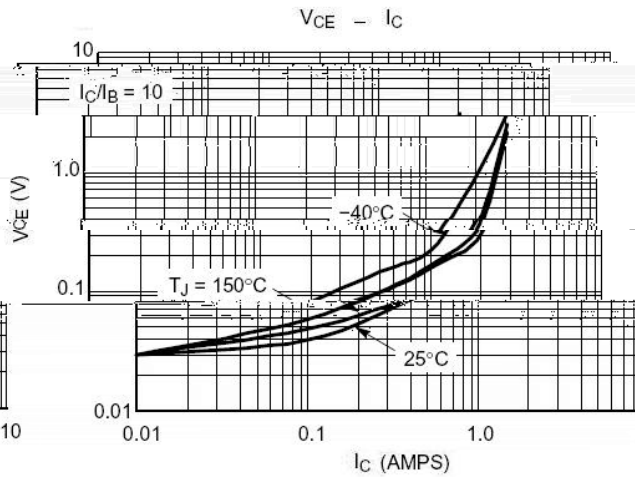
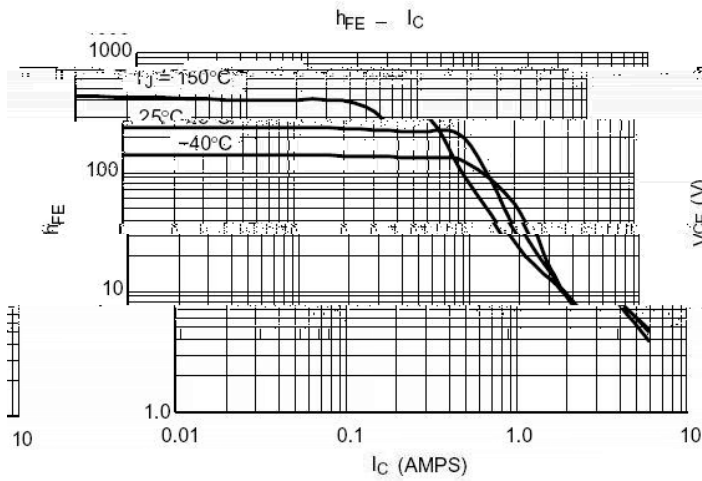
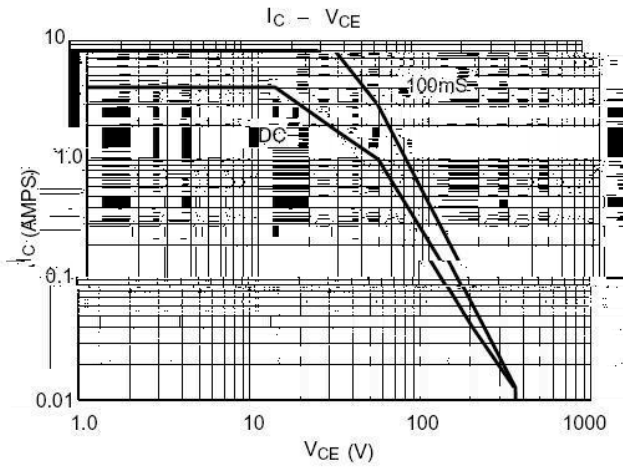
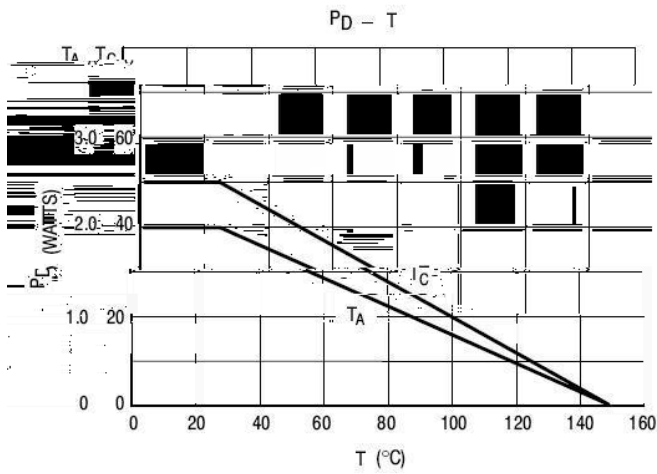
/ h_{FE} Classifications & Marking

See Marking Instructions.

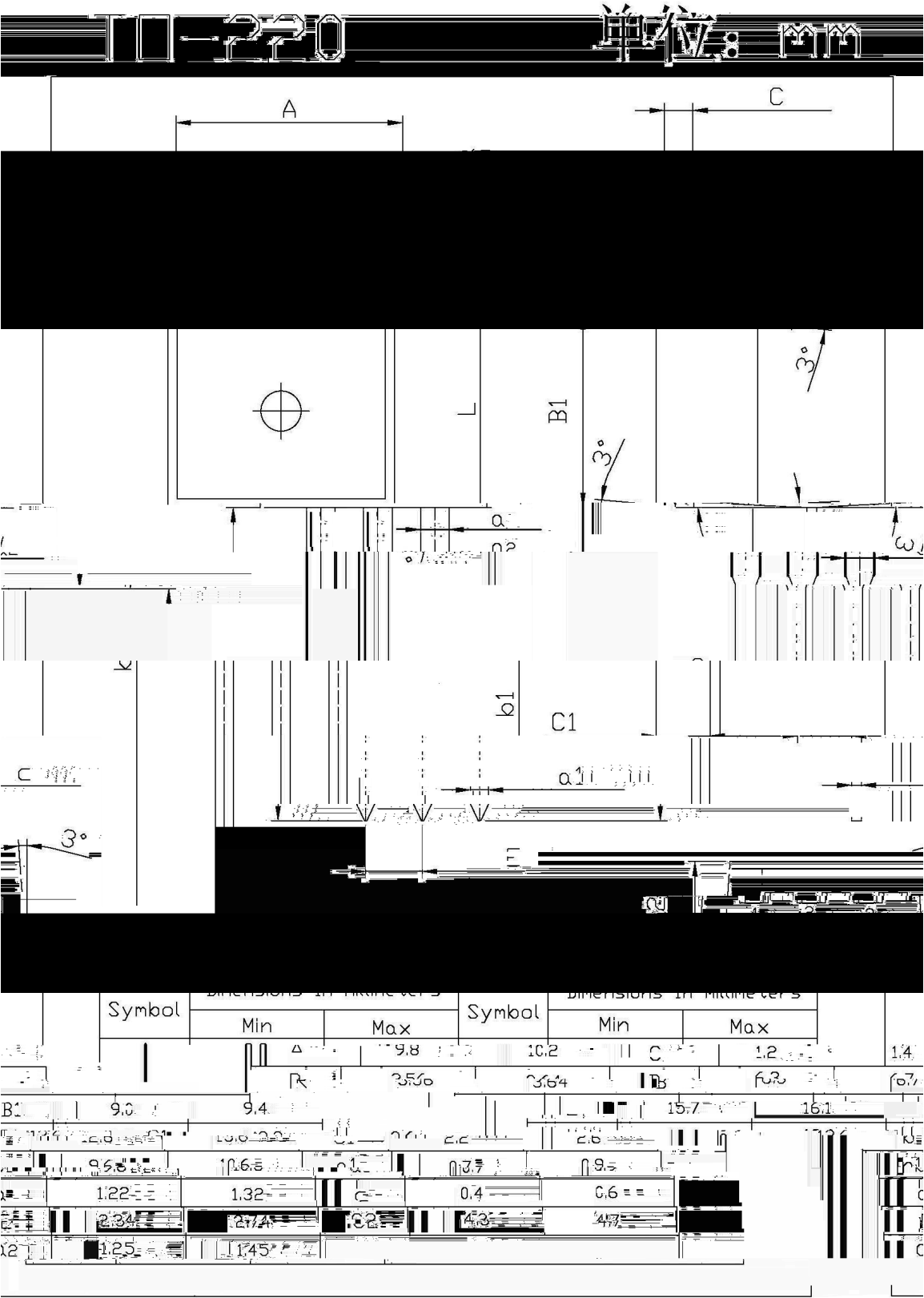
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-350	V
Collector to Emitter Voltage	V_{CEO}	-350	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-4.0	A
Base Current - Continuous	I_B	-1.0	A
Collector Power Dissipation	P_D	2.0	W
	$P_D(T_c=25^\circ\text{C})$	50	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-65 150	
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.5	/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	62.5	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage*	$*V_{CEO}$	$I_C=-10\text{mA}$ $I_B=0$	-350			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-350\text{V}$ $I_E=0$			-10	μA
Emitter Cut-Off Current	I_{EBO}	$V_{BE}=-5\text{V}$ $I_C=0$			-10	μA
DC Current Gain	$*h_{FE(1)}$	$V_{CE}=-5\text{V}$ $I_C=-0.5\text{A}$	100		500	
	$*h_{FE(2)}$	$V_{CE}=-5\text{V}$ $I_C=-0.1\text{A}$	100			
	$*h_{FE(3)}$	$V_{CE}=-5\text{V}$ $I_C=-1\text{A}$	5.0			
	$*h_{FE(4)}$	$V_{CE}=-5\text{V}$ $I_C=-2\text{A}$	10			
Collector to Emitter Saturation Voltage*	$*V_{CE(sat)}$	$I_C=-1\text{A}$ $I_B=-0.1\text{A}$			-0.5	V
Base to Emitter On Voltage*	$*V_{BE(on)}$	$V_{CE}=-5\text{V}$ $I_C=-1\text{A}$			-1.0	V
Transition Frequency	f_T	$V_{CE}=-10\text{V}$ $I_C=-500\text{mA}$ $f=1\text{MHz}$	30			MHz

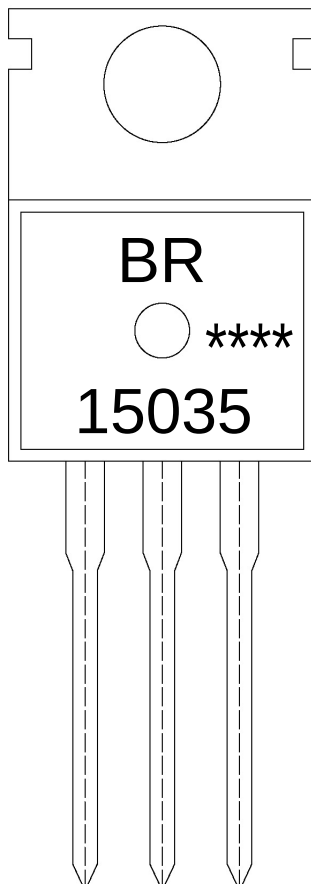
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

15035

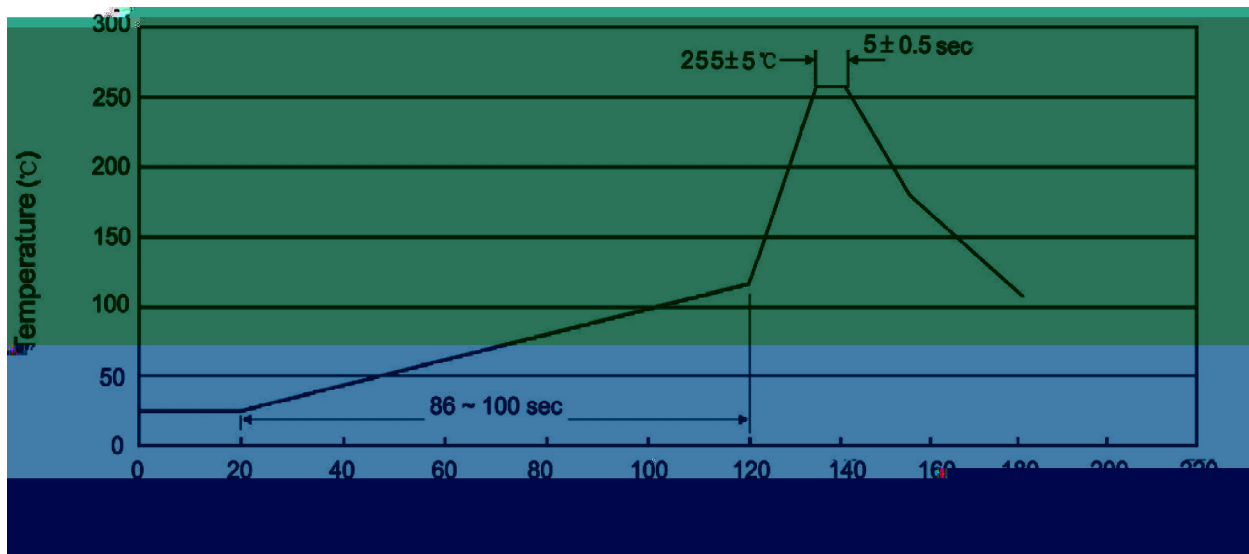
Note:

BR: Company Code

15035: Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--|---|
| 1 | 25 | 150 | 60 | 90sec; | 1. Preheating: 25~150 , Time: 60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2. Peak Temp.: 255±5 , Duration: 5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.: 270±5 Time: 10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

/ Notices